

UNITED STATES  
SECURITIES AND EXCHANGE COMMISSION  
Washington, DC 20549

**FORM 8-K**

**CURRENT REPORT**  
Pursuant to Section 13 or 15(d) of the  
Securities Exchange Act of 1934

**Date of Report (Date of earliest event reported)**

**May 27, 2014**

**AMKOR TECHNOLOGY, INC.**

(Exact name of registrant as specified in its charter)

**DELAWARE**

(State or Other Jurisdiction of  
Incorporation)

**000-29472**

(Commission File Number)

**23-1722724**

(IRS Employer  
Identification No.)

**1900 SOUTH PRICE ROAD  
CHANDLER, AZ 85286**

(Address of Principal Executive Offices, including Zip Code)

**(480) 821-5000**

(Registrant's telephone number, including area code)

Check the appropriate box below if the Form 8-K filing is intended to simultaneously satisfy the filing obligation of the registrant under any of the following provisions:

- Written communications pursuant to Rule 425 under the Securities Act (17 CFR 230.425)
  - Soliciting material pursuant to Rule 14a-12 under the Exchange Act (17 CFR 240.14a-12)
  - Pre-commencement communications pursuant to Rule 14d-2(b) under the Exchange Act (17 CFR 240.14d-2(b))
  - Pre-commencement communications pursuant to Rule 13e-4(c) under the Exchange Act (17 CFR 240.13e-4(c))
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**Item 8.01. Other Events.**

On May 27, 2014, Amkor and Carsem (M) Sdn Bhd jointly announced the settlement of the litigation initiated by Amkor against Carsem alleging infringement of Amkor's *MicroLeadFrame*<sup>®</sup> (MLF) patents. The parties have entered into a settlement agreement to end all pending proceedings related to the dispute and Carsem will pay Amkor an agreed sum for such settlement. Under the terms of the agreement, Amkor and Carsem have granted each other non-exclusive licenses to their respective MLF and MLP patents worldwide.

Additional information about the settlement is contained in the press release attached hereto as Exhibit 99.1.

**Item 9.01. Financial Statements and Exhibits.**

(d) Exhibits.

99.1 Press release dated May 27, 2014, which is furnished (not filed) herewith.

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**SIGNATURES**

Pursuant to the requirements of the Securities Exchange Act of 1934, the registrant has duly caused this report to be signed on its behalf by the undersigned hereunto duly authorized.

Date: May 27, 2014

Amkor Technology, Inc.

/s/ Gil C. Tily

Gil C. Tily

*Executive Vice President*

*Chief Administrative Officer and General Counsel*

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## Index to Exhibits

Exhibit	Description
99.1	Text of Press Release dated May 27, 2014, which is furnished (not filed) herewith.

### Amkor Technology And Carsem Jointly Announce Settlement

CHANDLER, Ariz. and IPOH, Malaysia – May 27, 2014 - Amkor Technology, Inc. (Nasdaq: AMKR) and Carsem (M) Sdn Bhd today jointly announced the settlement of the litigation initiated by Amkor against Carsem alleging infringement of Amkor's *MicroLeadFrame*® (MLF) patents.

The parties have entered into a settlement agreement to end all pending proceedings related to the dispute and Carsem will pay Amkor an agreed sum for such settlement.

Under the terms of the agreement, Carsem and Amkor have granted each other non-exclusive licenses to their respective MLF and MLP patents worldwide.

"We are pleased that Carsem has agreed to take a license to our industry leading MLF patent family, and that we can finally close this long-running dispute," said Steve Kelley, Amkor's president and chief executive officer.

"With this settlement, we are happy that the dispute is behind us and our customers will have the benefits of the license," said Peter Yates, managing director of Carsem.

#### About Amkor

Amkor is a leading provider of semiconductor packaging and test services to semiconductor companies and electronics OEMs. More information about Amkor is available from the company's filings with the Securities and Exchange Commission and on Amkor's website: [www.amkor.com](http://www.amkor.com).

#### About Carsem

Carsem is a leading provider of turnkey packaging and test services to the semiconductor industry, and offers one of the widest ranges of package & test portfolios in the world. To meet the growing demands of the telecommunications and wireless markets for smaller, faster, thermally-efficient devices, Carsem's portfolio includes many advanced technologies, such as the Micro Leadframe Package (MLP), Flip Chip on Leadframe (FCOL™), an SiP (System-in-Package) Technology, Cavity-Package Motion and Pressure Sensor technologies as well as stacked-die capability. Carsem also offers a full range of turnkey test services for RF, mixed-signal, linear, digital and power devices. Our factories maintain world-class quality standards having achieved SAC Level 1, ISO-9001, ISO-14001, QS-9000, TS16949, ANSI-ESD S20.20 certifications, and are supported with a global network of sales and engineering support offices. Carsem is a member of the Hong Leong Group with factories located in Ipoh, Malaysia, Suzhou, China and sales offices across the USA, the UK, China, Malaysia and Taiwan. More information is available on the Carsem website: [www.carsem.com](http://www.carsem.com).

#### Contacts

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